L Number	Hits	Search Text	DB	Time stamp
-	3	5497291.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/12/05 15:52
-	3	3771101.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/12/05 11:28
-	3	5295044.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/12/05 11:28
-	7	5295044.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/12/05 11:37
-	18	("4356532" I "4956746" I "4969066" I "5057971" I "5101322" I "5172303").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/12/05 11:38
-	6	5497291.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/12/05 11:43
-	6	5497291.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/12/05 11:47
-	3	"5382830".PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/12/05 11:47
-	2	6178095.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/12/05 16:42
-	448	aluminum and gold near(wire near bond$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/12/05 16:44

L Number	Hits	Search Text	DB	Time stamp
-	1401	361/736	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/12/03 11:42
-	332	361/736 and (ceramic or epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/29 14:36
-	273	361/719.ccls. and (ceramic or epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/29 14:52
-	124	361/720.ccls. and (ceramic or epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/29 14:57
-	35	361/739.ccls. and (ceramic or epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/29 15:01
-	140	361/752.ccls. and (ceramic or epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/29 15:12
-	14	361/742.ccls. and (ceramic or epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/29 15:14
-	176	361/784.ccls. and (ceramic or epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/29 15:21
-	121	361/785.ccls. and (ceramic or epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/29 15:25
-	36	361/789.ccls. and (ceramic or epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/29 15:29
-	102	361/790.ccls. and (ceramic or epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/29 15:33
-	32	361/791.ccls. and (ceramic or epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/29 15:38
-	202	361/772.ccls. and (ceramic or epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/29 15:42
-	152	361/773.ccls. and (ceramic or epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/29 15:45
-	204	361/774.ccls. and (ceramic or epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/29 15:49

-	130	361/803.ccls. and (ceramic or epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/29 15:52
-	19	361/804.ccls. and (ceramic or epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/29 15:53
-	515	174/52.2.ccls. and (ceramic or epoxy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/29 15:54
-	165	174/52.2.ccls. and (ceramic or epoxy) and (pins or connectors)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/29 16:01
-	334	174/52.4.ccls. and (ceramic or epoxy) and (pins or connectors)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/29 16:42
-	6230	power near module	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/29 16:05
-	1046	power near module and pins	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/29 16:26
-	5	439/928.ccls. and (ceramic or epoxy) and (pins or connectors)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/29 16:44
-	2	439/928.1.ccls. and (ceramic or epoxy) and (pins or connectors)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/29 16:44
-	87	439/928.1.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/29 16:46
-	153	439/928.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/29 16:50
-	701	257/691.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/29 16:51
-	2	"6178095"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/11/29 16:57